



# IPC-TM-650 TEST METHODS MANUAL

Number <b>2.2.7</b>	
Subject <b>Hole Size Measurement, Plated</b>	
Date <b>5/86</b>	Revision <b>A</b>
Originating Task Group <b>Printed Board Test Methods Task Group (7-11d)</b>	

**1.0 Scope** To measure the inside diameter of plated through holes in printed wiring boards.

**2.0 Applicable documents** None.

**3.0 Test Specimen** Production board or test pattern, number and design of holes shall be determined by agreement between vendor and customer or applicable drawings.

## 4.0 Apparatus

**4.1 Stereoscopic microscope** With 20x magnification micrometer scale eye piece and illuminator.

## 5.0 Procedure

**5.1 Measurement** Set the microscope on 20x magnification and measure the inside diameter of the hole from one side to the other side at the largest point.

**5.2 Evaluation of test** Record measurements and note if voids and nodules were present.